

Layer Name	Deriver Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
Top Layer	(.GTL)	1.4mil	
Bottom Layer	(.GBL)	1.4mil	FR-4
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION	
BOARD SIZE	(REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
<u>1000MIL</u>	X <u>1000MIL</u>
Number of Layers :	<u>2</u>
MIN. TRACK WIDTH:	<u>8</u> MIL
MIN. CLEARANCE:	<u>8</u> MIL
MIN. VIA PAD SIZE:	<u>24</u> MIL
MINIMUM ANNUAL RING 0.05mm (2MIL) EXTERNAL	
PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: MECHANICAL +/- 5 MIL, HOLES +/- 3 MIL	

MATERIAL: ☐ FR-408 ☒ FR-4 High Tg ☐ OTHER _____

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER _____

TOLERANCE: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____

BOW & TWIST: ☒ ANSI IPC-6012 TYPE 3 CLASS 2
☐ OTHER +/- _____

COPPER THICKNESS (FINISHED):

OUTER:	<input checked="" type="checkbox"/> 1.4MIL (1oz)	<input type="checkbox"/> 2MIL (1.4oz)	<input type="checkbox"/> 2.8MIL (2oz)
INNER SIGNAL:	<input checked="" type="checkbox"/> 1.4MIL (1oz)	<input type="checkbox"/> 2.8MIL (2oz)	<input type="checkbox"/> N/A

DRILLING:
REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES
PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER

BOARD FINISH:
 SILKSCREEN: ☒ TOP ☒ BOTTOM
 SILKSCREEN COLOR: ☒ WHITE ☐ OTHER _____
 SOLDER RESIST COLOR:
☒ GREEN ☐ BLUE ☐ OTHER _____

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENEPIG
☐ IMM. TIN/SILVER OR EQUIV ☐ OTHER _____

ARRAY/PANEL: ☐ CUT AND TRIM PER MECH LAYER 1
☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs
TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI IPC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3

☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER

ADDITIONAL REQUIREMENTS:
MICROSECTION: ☐ YES
BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER
MANUFACTURER'S UL: ☐ RAIL ☐ METAL ☒ SILK



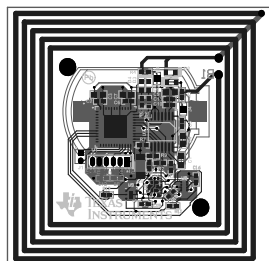
PROJECT TITLE:	NFC Authentication
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DESIGNED FOR:
Public Release

FILE NAME:
ISE4003 E1 PCB.PcbDoc

ENGINEER:	LAYOUT BY:
Evan Cornell	Krypton

SCALE: 1.00	ALTIUM DESIGNER VERSION: 10.0.0.27009
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ASSEMBLY VARIANT:

ALL ARTWORK VIEWED FROM TOP SIDE		BOARD #:	ISE4003	REV:	E1	SUN REV: Not In VersionControl
Multilayer Composite Print	GENERATED	:	10/22/2014	3:55:38 AM	TEXAS INSTRUMENTS	

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